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(54) Title: EMBEDDED COMPONENT INTERPOSER OR SUBSTRATE COMPRISING DISPLACEMENT COMPENSATION TRACES (DCTs) AND METHOD OF MAKING THE SAME

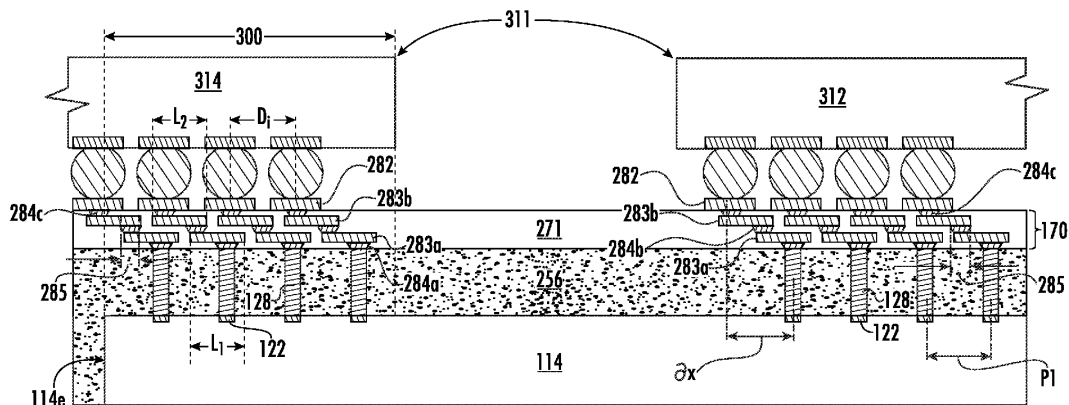


FIG. 9D

(57) Abstract: A method of making a substrate comprising an embedded component and further comprising a region of displacement compensation traces (DCTs) may comprise the following. A component comprising conductive contacts. Measuring a shift of the component. Forming a plurality of interconnect pads over the component according to a nominal design position. Forming the region of DCTs may comprise at least one arrangement of DCTs with unit specific patterning such that the arrangement of DCTs is coupled to, and extends between, the conductive contacts and the interconnect pads. The arrangement of DCTs may compensate for the measured shift of the component and a majority of the arrangement of DCTs does not extend beyond a shared footprint of the component and the interconnect pad region.

[Continued on next page]

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